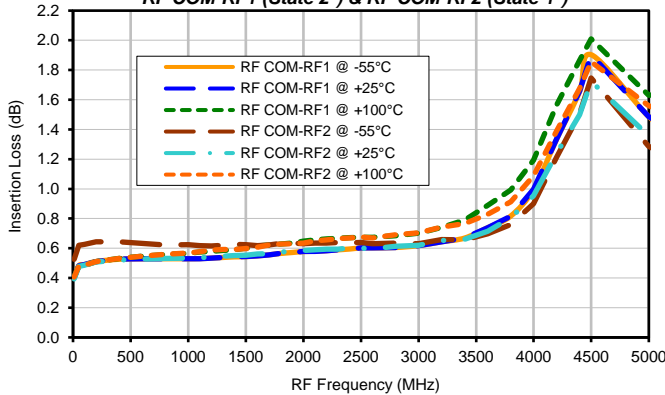
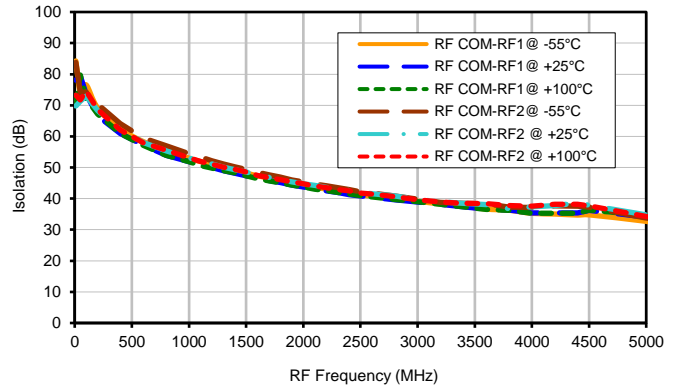


Typical Performance Data ⁽¹⁾

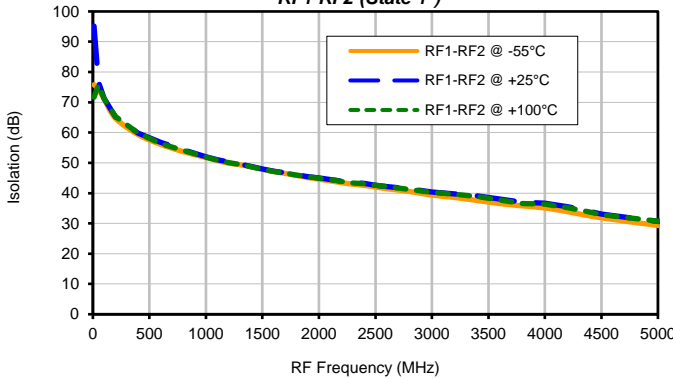
Insertion Loss @ VDD=+5V, VEE =-5V over Temperature
RF COM-RF1 (State 2*) & RF COM-RF2 (State 1*)



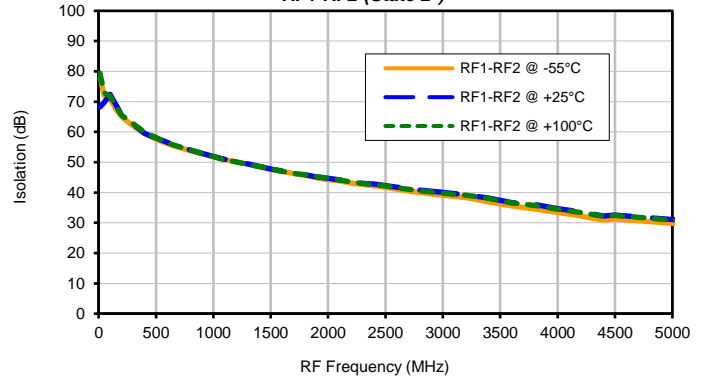
Isolation @ VDD=+5V, VEE =-5V over Temperature
RF COM-RF1 (State 1*) & RF COM-RF2 (State 2*)



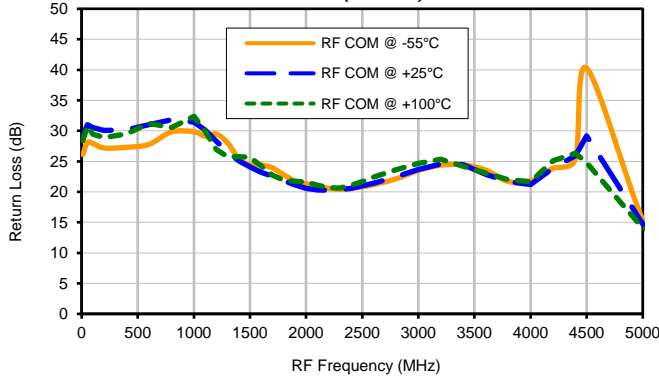
Isolation @ VDD=+5V, VEE =-5V over Temperature
RF1-RF2 (State 1*)



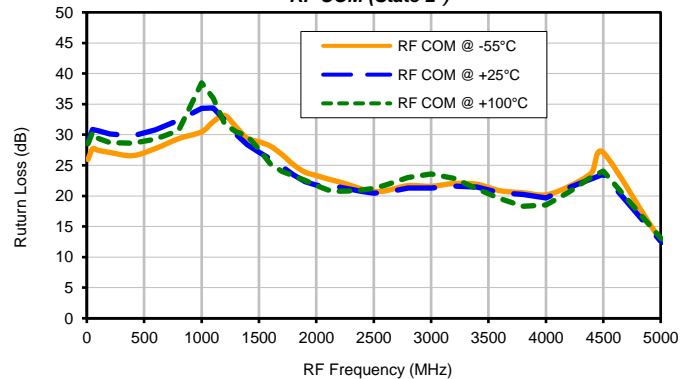
Isolation @ VDD=+5V, VEE =-5V over Temperature
RF1-RF2 (State 2*)



RL @ VDD=+5V, VEE =-5V over Temperature
RF COM (State 1*)



RL @ VDD=+5V, VEE =-5V over Temperature
RF COM (State 2*)

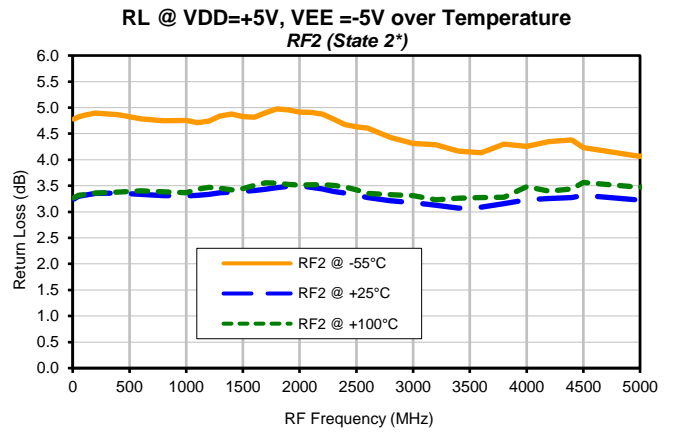
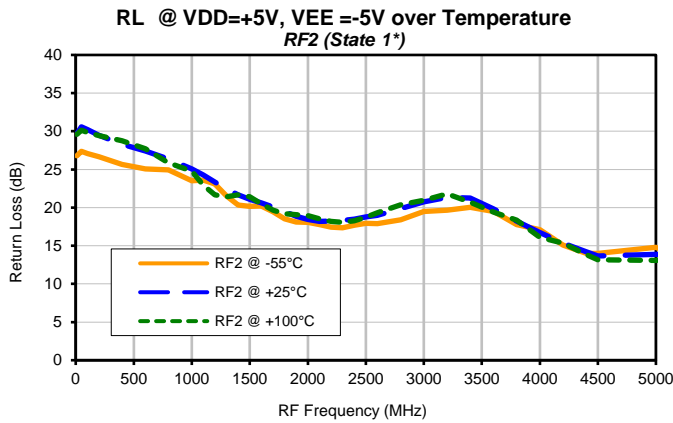
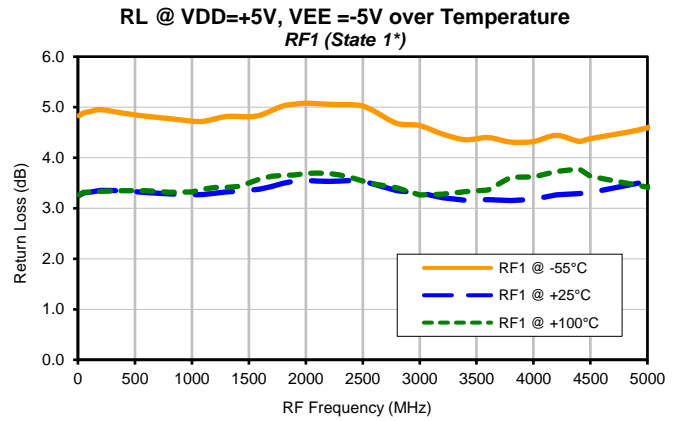
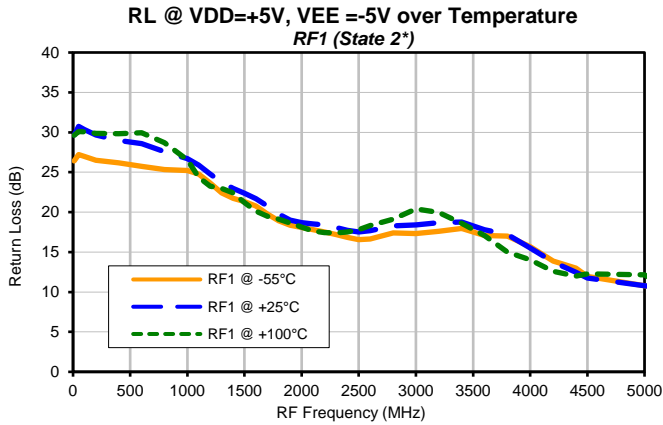


(1) Test data of Die packaged in industry standard, 3.25x3.25 mm, 8-lead MCLP package

*Note:

STATE	CONTROL INPUT	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF

Typical Performance Data ⁽¹⁾



(1) Test data of Die packaged in industry standard, 3.25x3.25 mm, 8-lead MCLP package

*Note:

STATE	CONTROL INPUT	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF